

Lecture #8. Fall, 2012

Electrochemical Energy Engineering

Scanning probe techniques (ch. 16)

Scanning tunneling microscopy (STM)

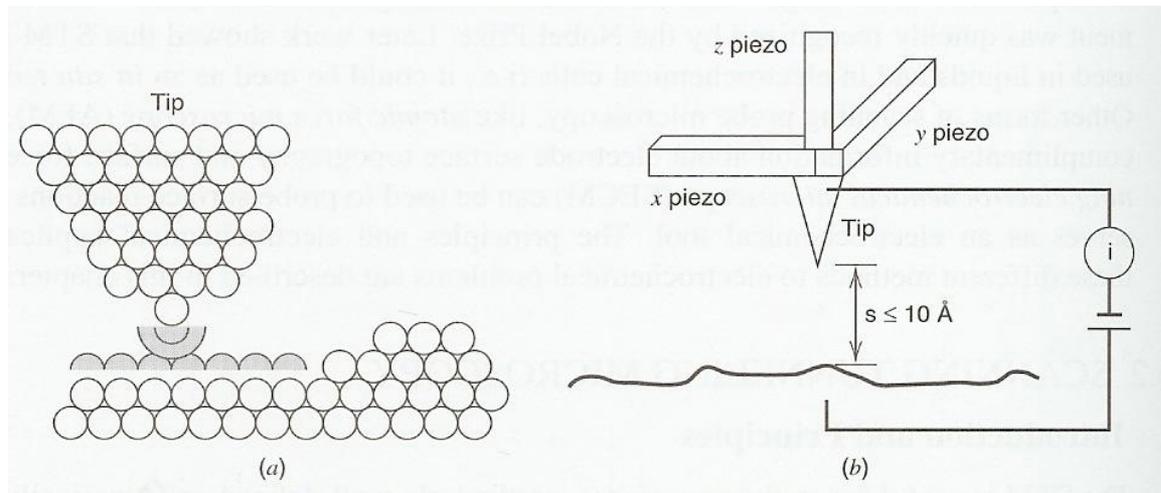
Atomic force microscopy (AFM)

Scanning electrochemical microscopy (SECM)

Scanning probe techniques

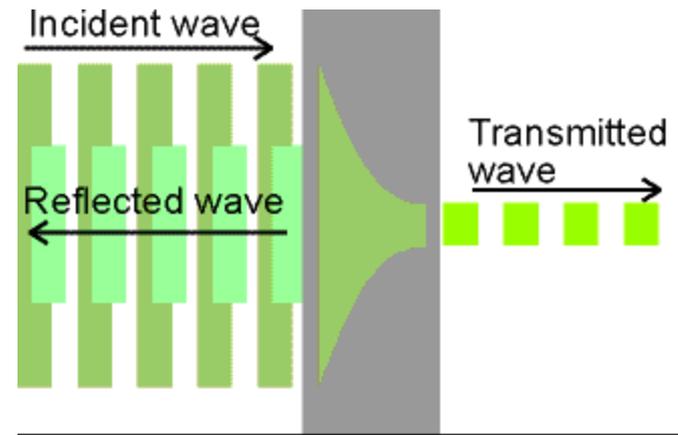
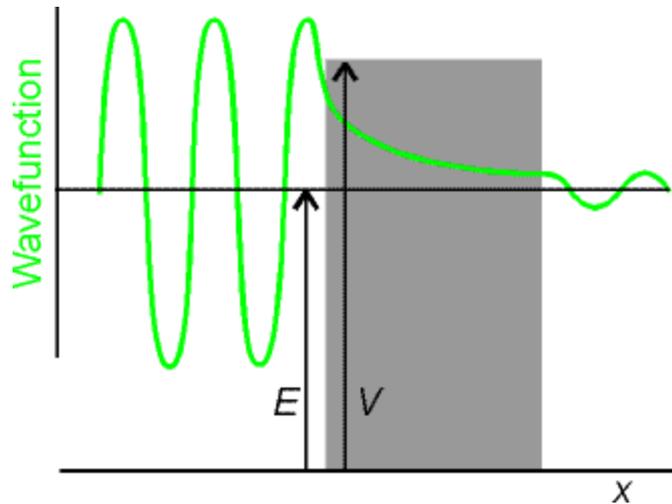
Microscopy: optical \rightarrow scanning electron or force \rightarrow STM, AFM
in situ vs. ex situ techniques

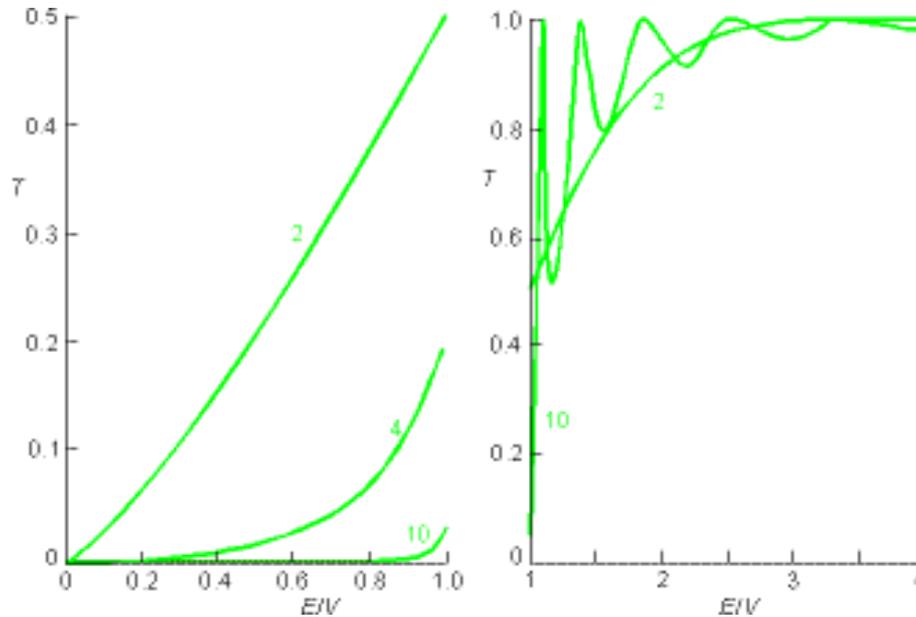
Scanning tunneling microscopy (STM)



Tunnelling

- if the potential energy of a particle does not rise to infinite in the wall & $E < V \rightarrow \Psi$ does not decay abruptly to zero
 - if the walls are thin $\rightarrow \Psi$ oscillate inside the box & on the other side of the wall outside the box \rightarrow particle is found on the outside of a container: leakage by penetration through classically forbidden zones “tunnelling”
- cf) C.M.: insufficient energy to escape





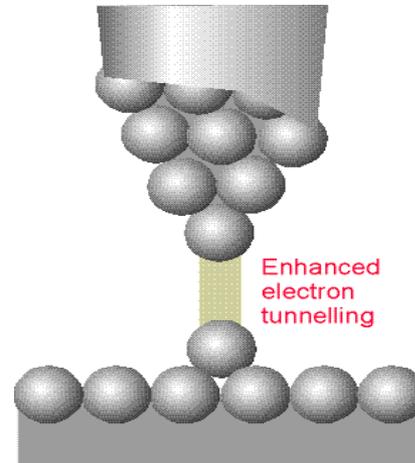
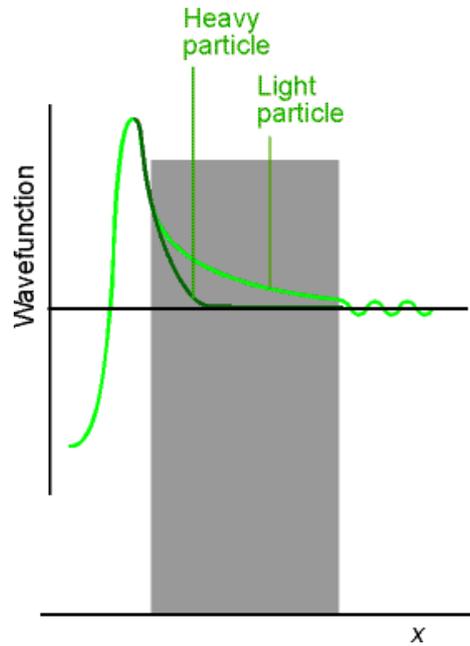
The transition probabilities for passage through a barrier. The horizontal axis is the energy of the incident particle expressed as a multiple of the barrier height. The curves are labelled with the value of $L(2mV)^{1/2}$. The graph on the left is for $E < V$ and that on the right for $E > V$. Note that $T = 0$ for $E < V$ whereas classically T would be zero. However, $T < 1$ for $E > V$, whereas classically T would be 1.

enhanced reflection (antitunnelling)

- high, wide barrier $\kappa L \gg 1$

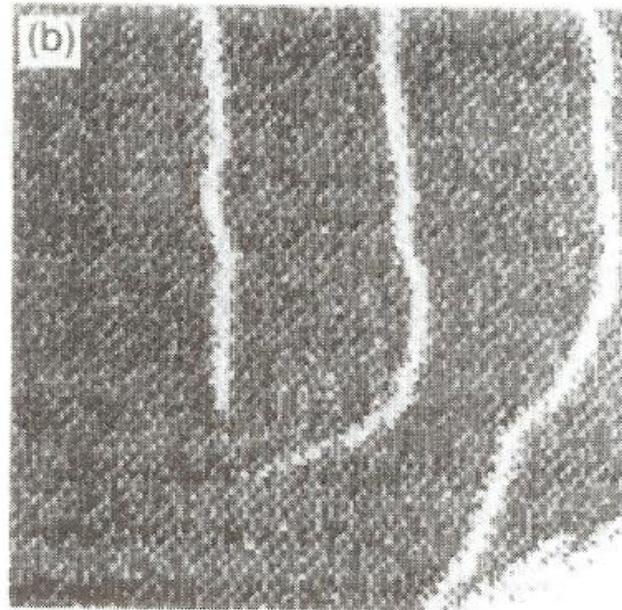
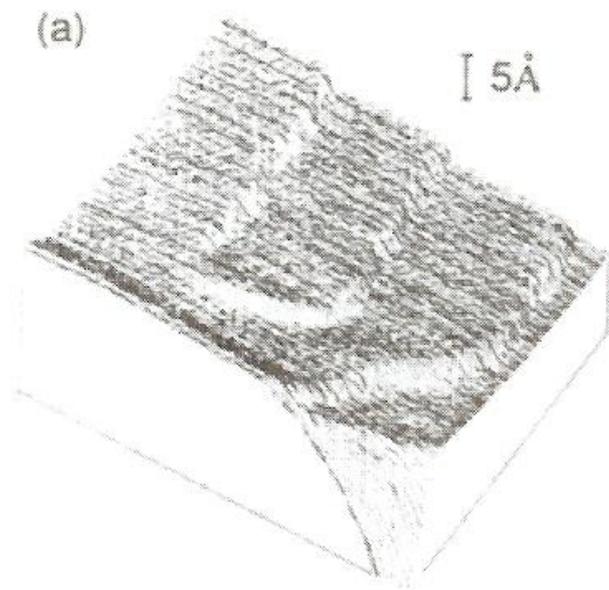
$\Rightarrow T$ decrease exponentially with thickness of the barrier, with $m^{1/2}$

\Rightarrow low mass particle \rightarrow high tunnelling *tunnelling is important for electron

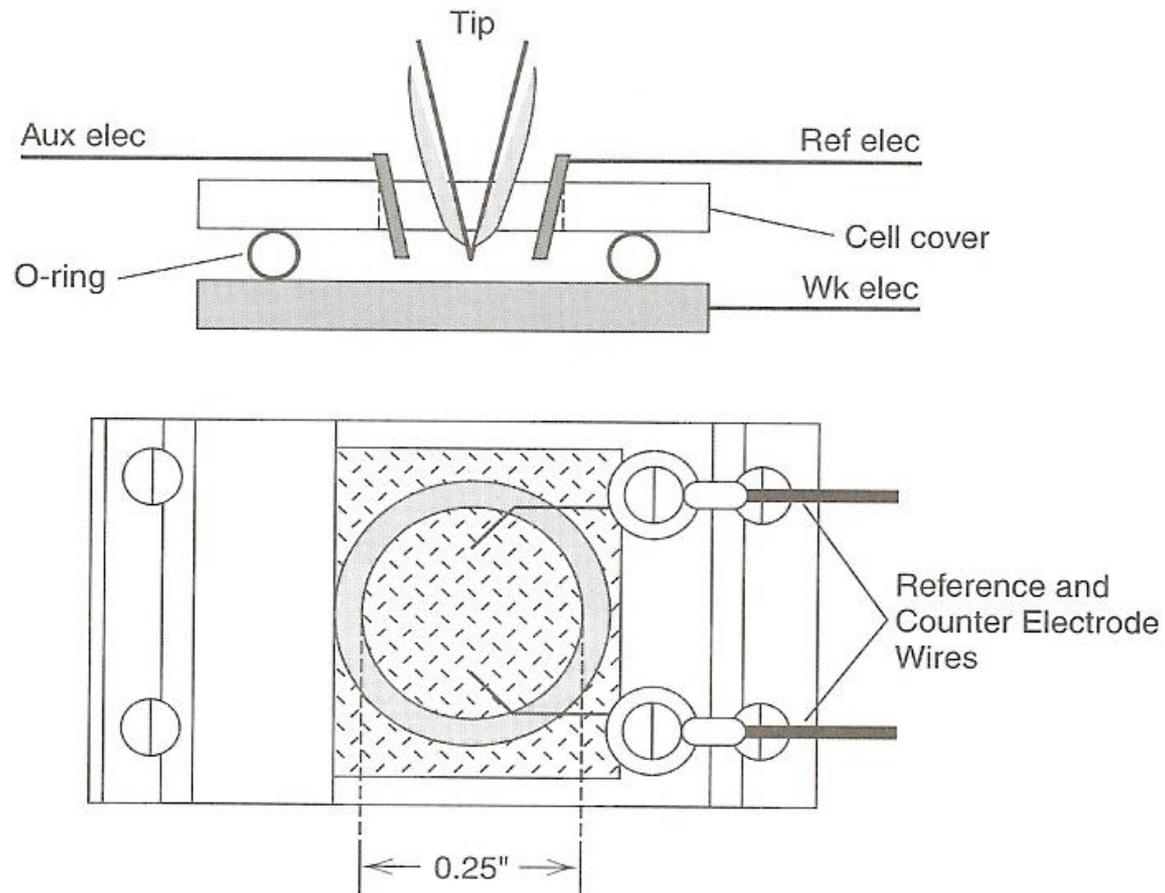


e.g) proton transfer reaction
STM (scanning tunnelling microscopy)
AFM (atomic force microscopy)

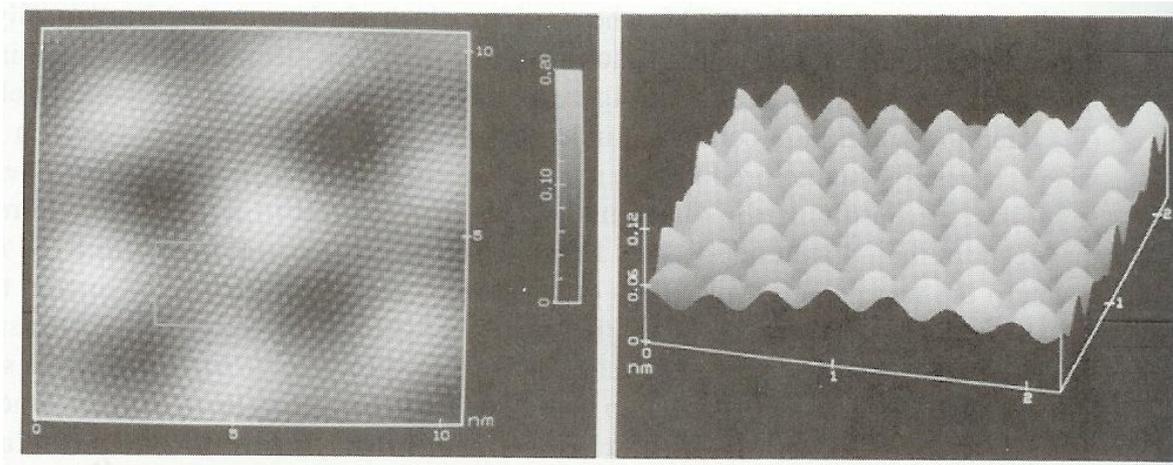
Au(111) at 0.7 V vs. NHE in HCl



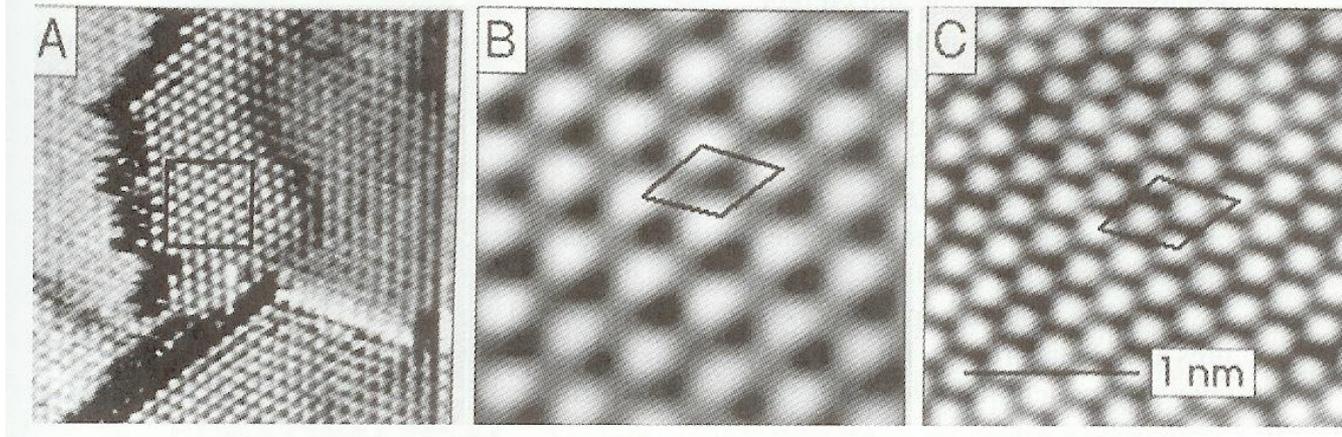
Electrochemical STM



STM images of HOPG



STM images of Pt(111) with I-adlattice in HClO_4



STM images of Cu(111): effect of etching

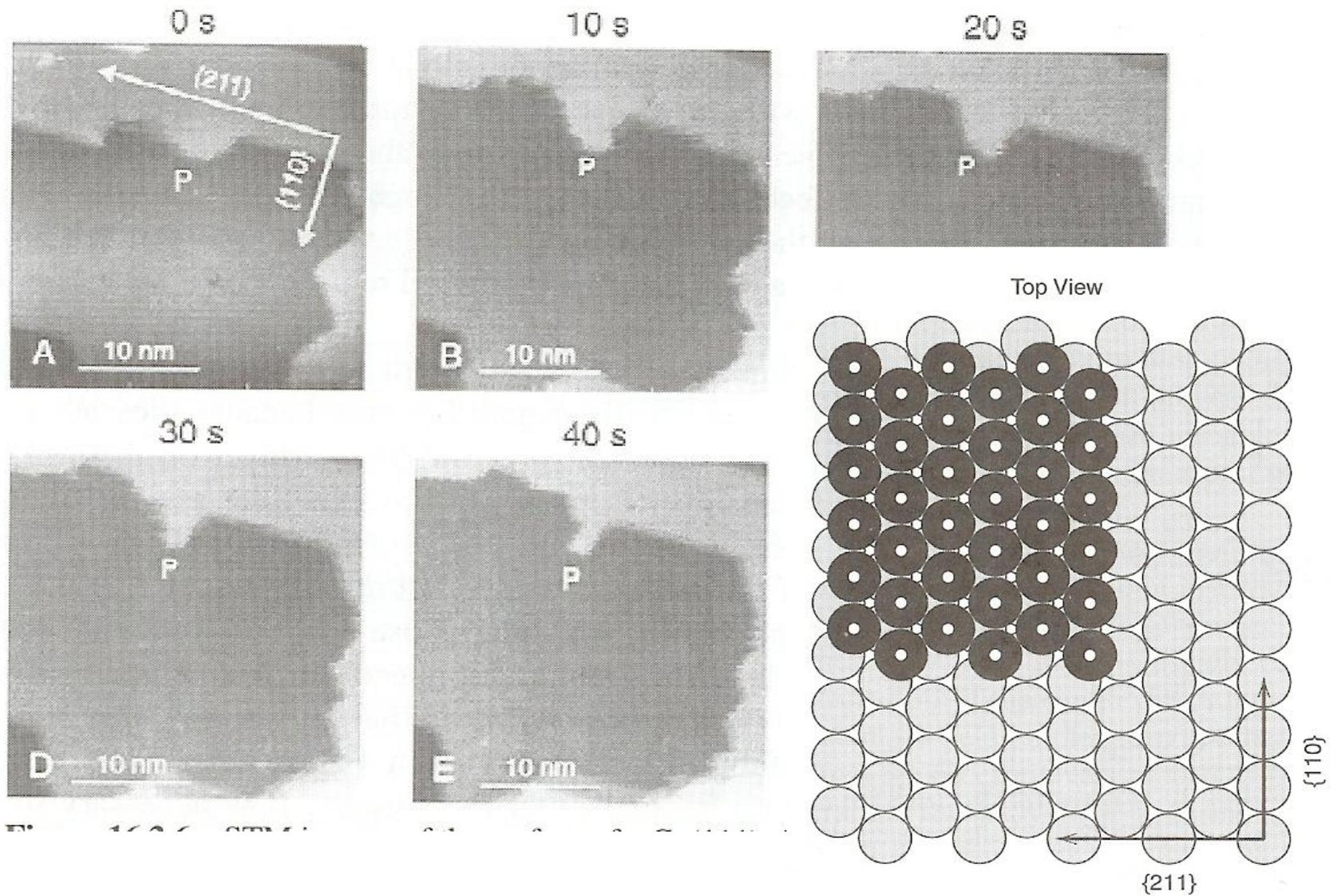
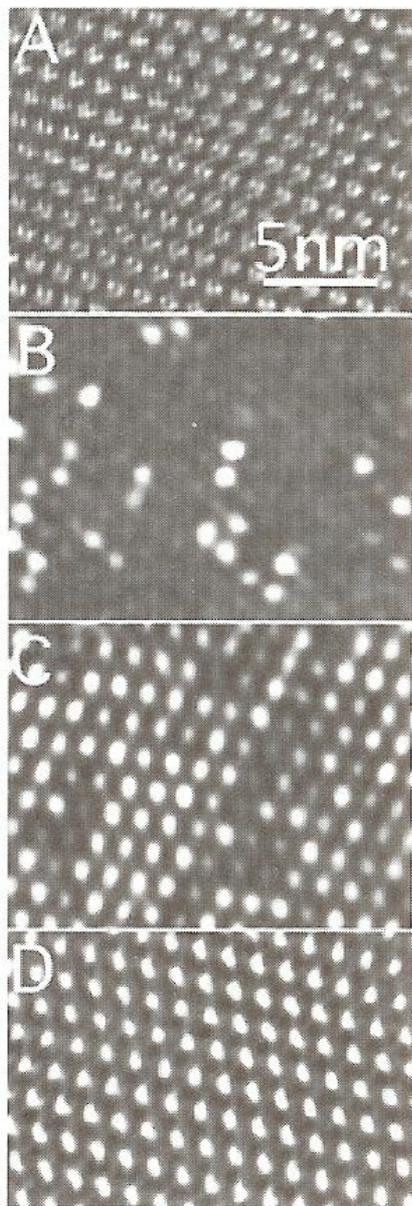
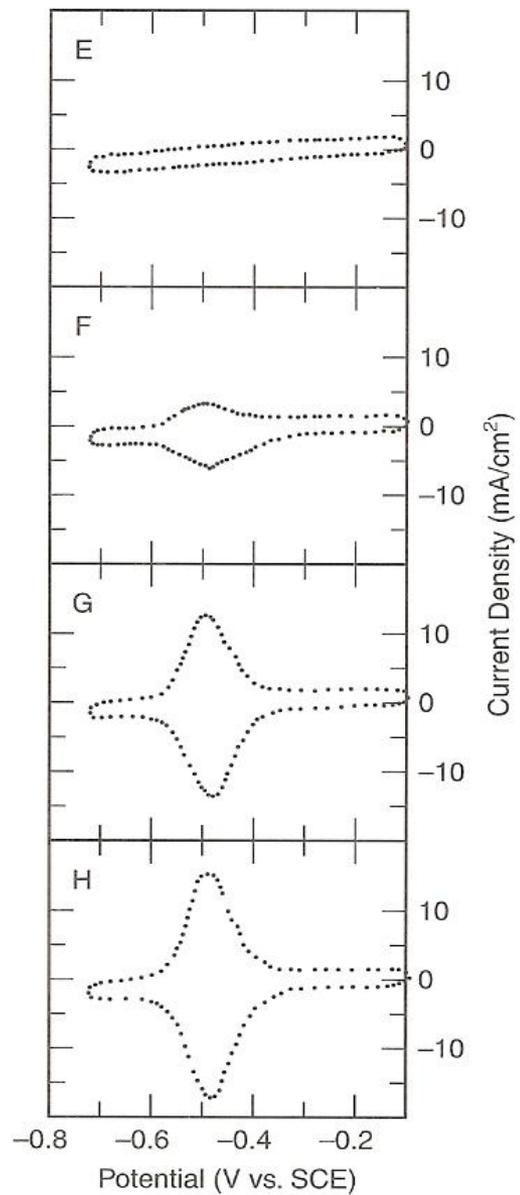


Fig. 1. STM images of Cu(111) surface after etching for 0 s (A), 10 s (B), 30 s (D), and 40 s (E).

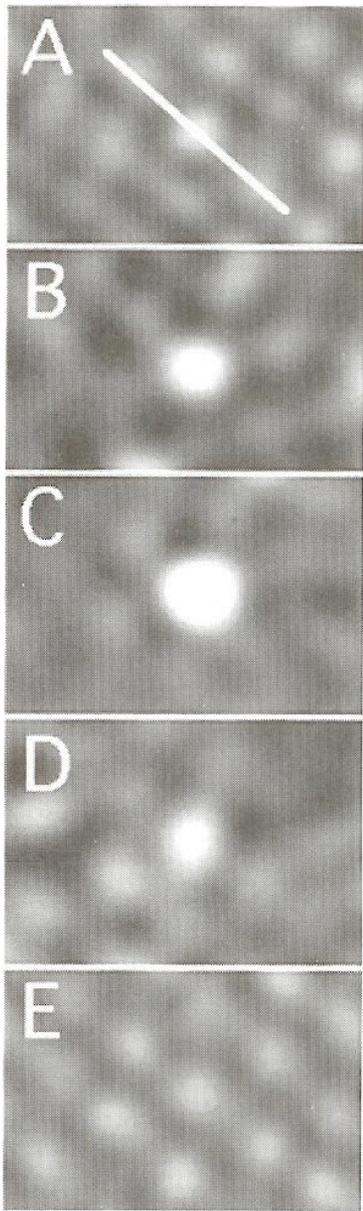
Fig. 2. Schematic diagram of the Cu(111) surface after etching for 40 s.



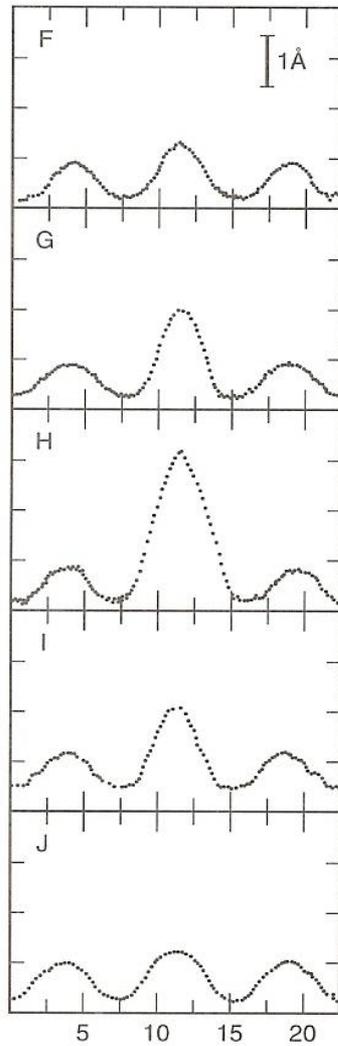
(a)



(b)



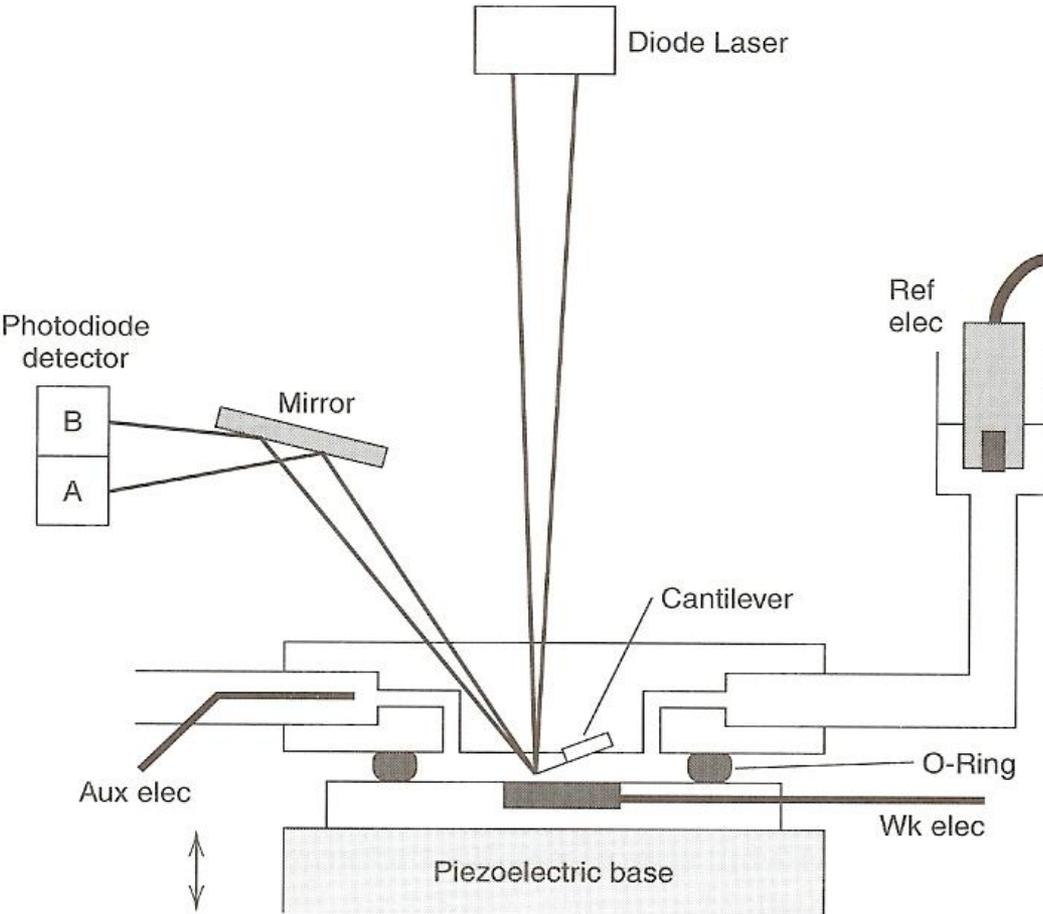
(a)



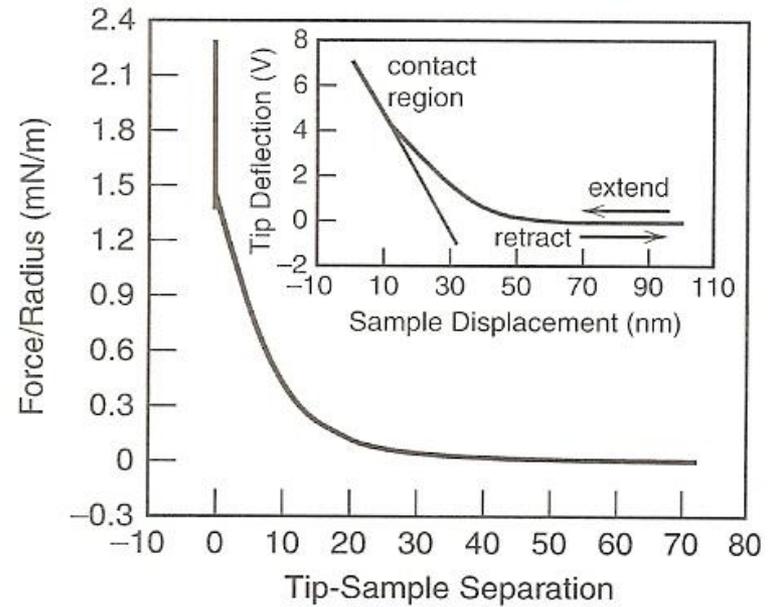
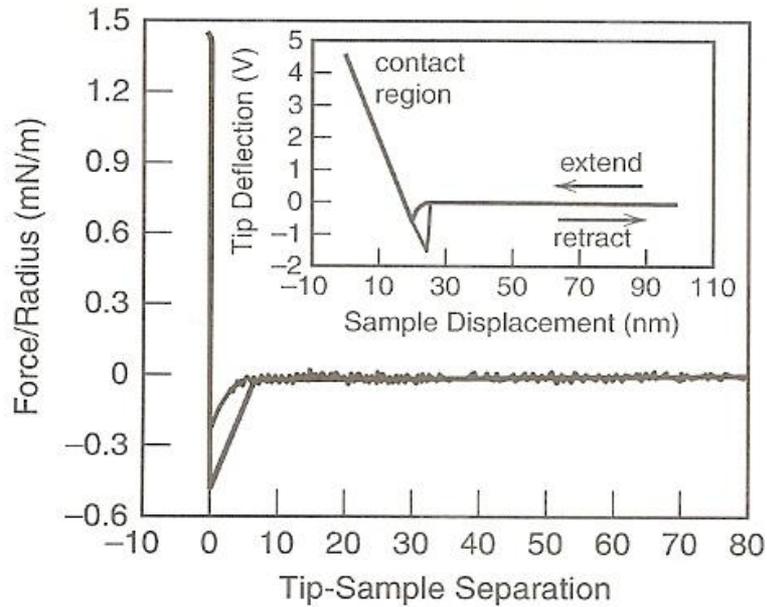
(Å)
(b)

Scanning tunneling spectroscopy (STS)

Atomic force microscopy (AFM)

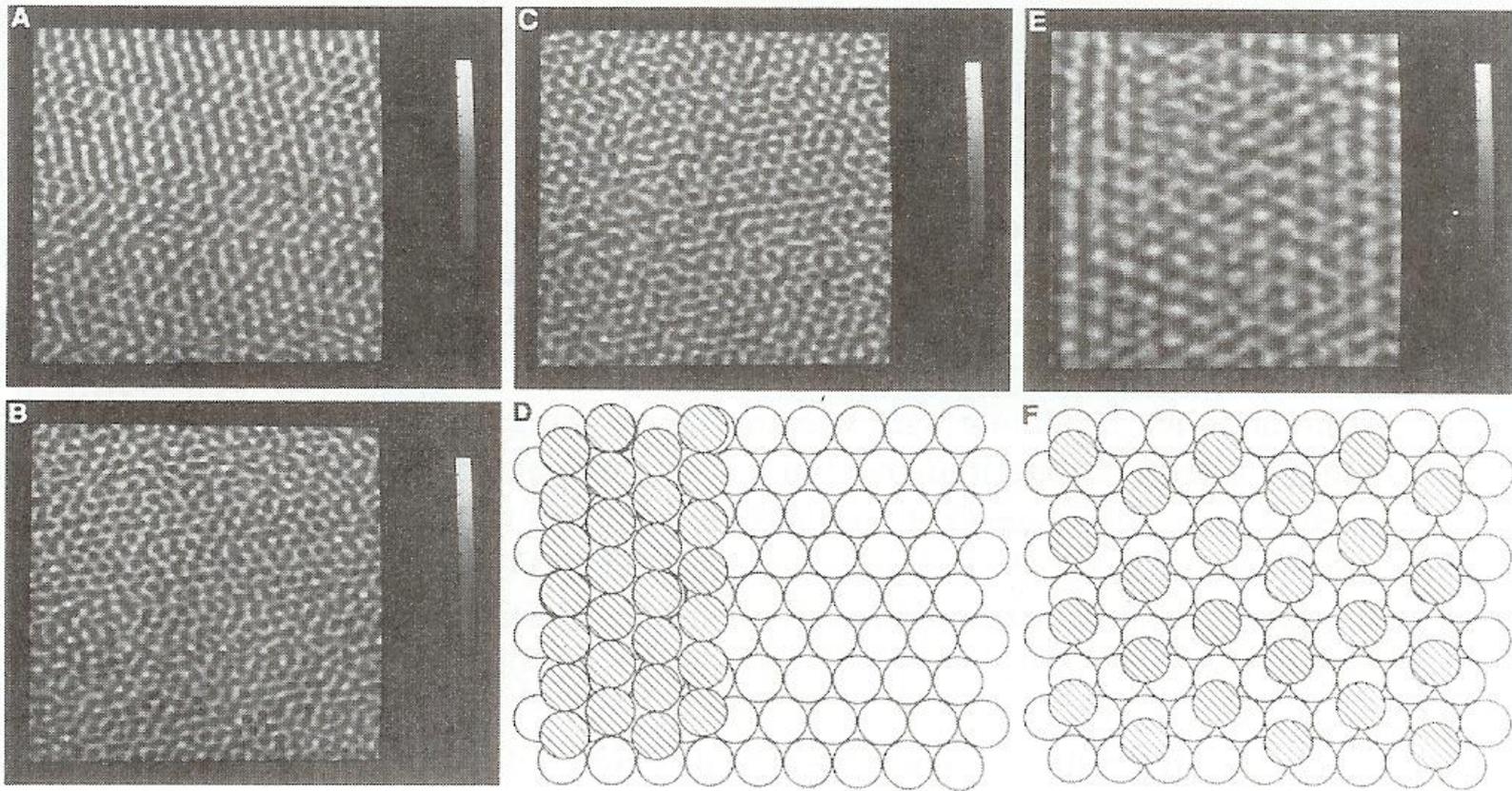


Cantilever displacement vs. z-deflection for (left) attractive interaction and (right) repulsive interaction

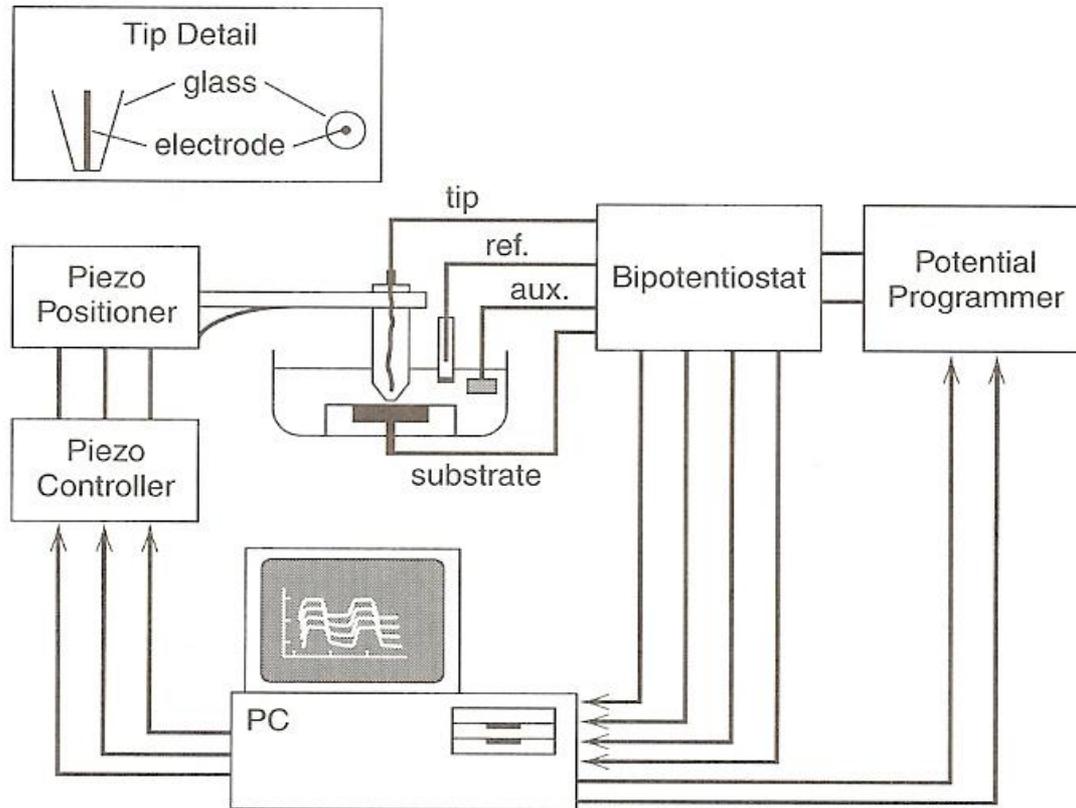


Electrochemical AFM

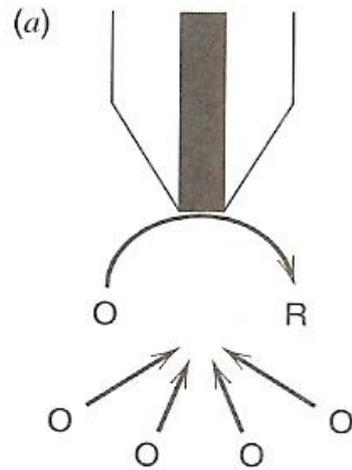
AFM of Cu underpotential deposition (UPD) on Au(111)



Scanning electrochemical microscopy (SECM)

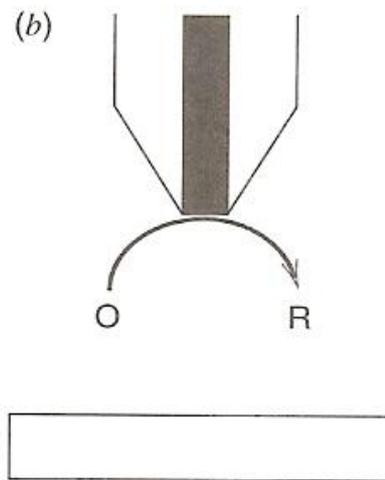


Principles of SECM



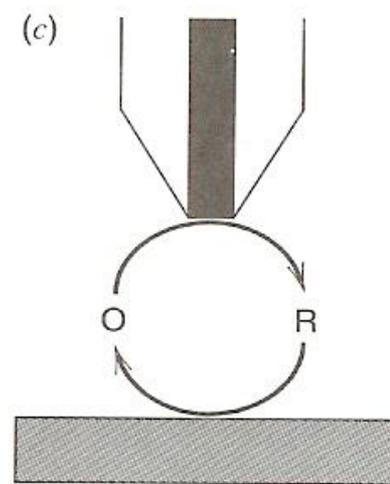
Hemispherical
Diffusion

$$i_{T,\infty} = 4nFDc_a$$



Blocking by
Insulating
Substrate

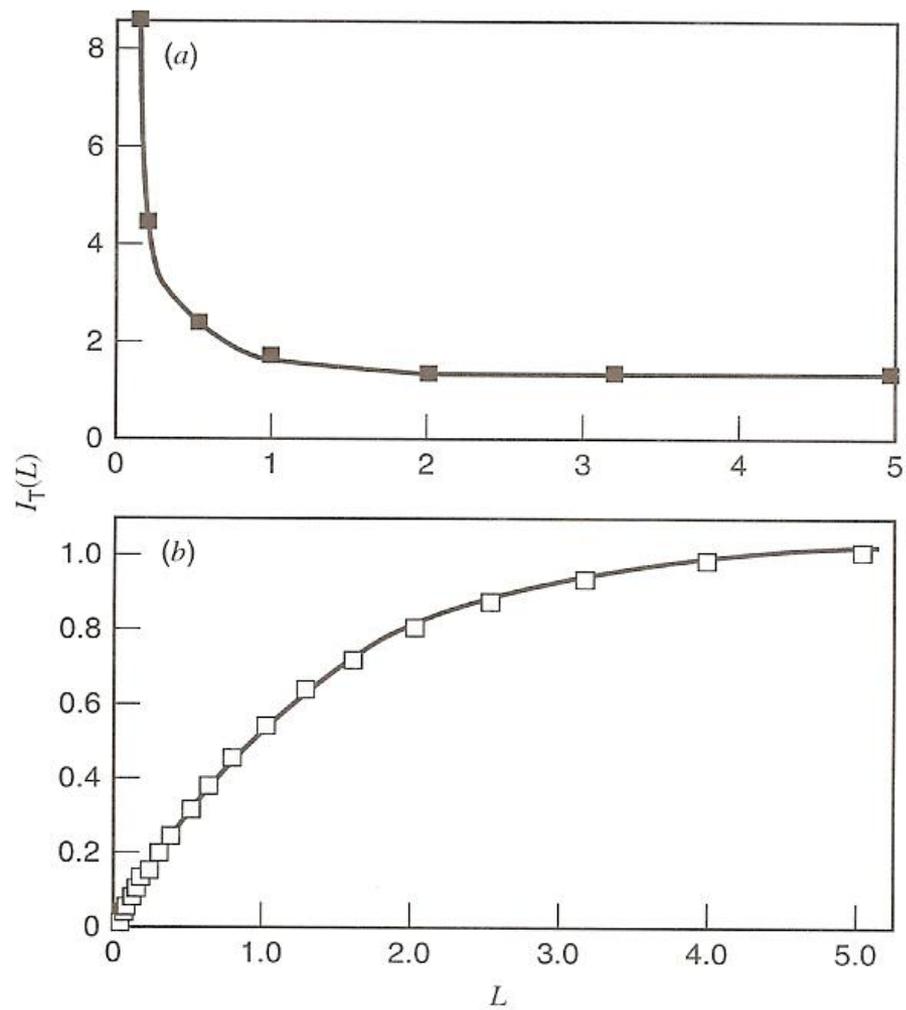
$$i_T < i_{T,\infty}$$

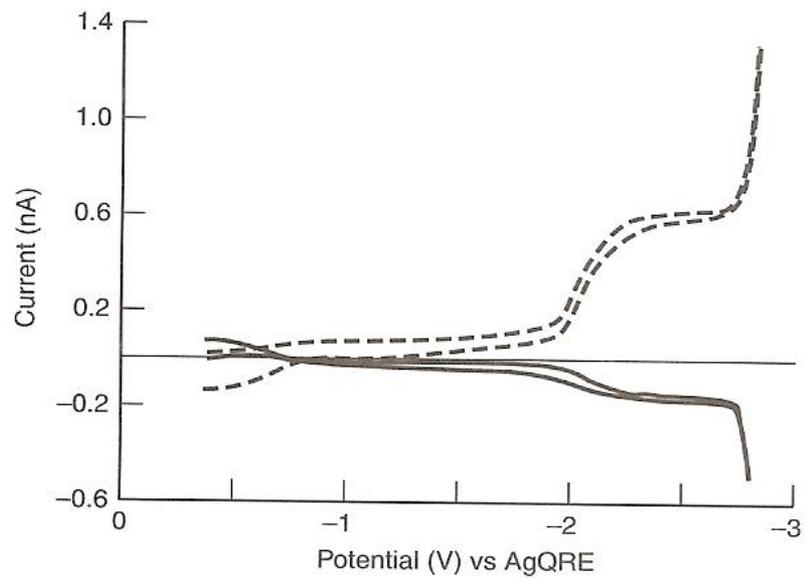
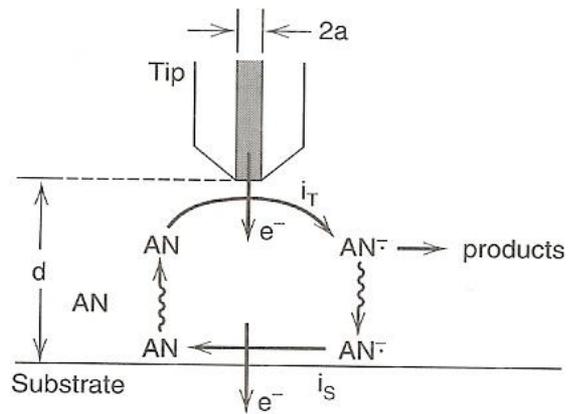


Feedback from
Conductive
Substrate

$$i_T > i_{T,\infty}$$

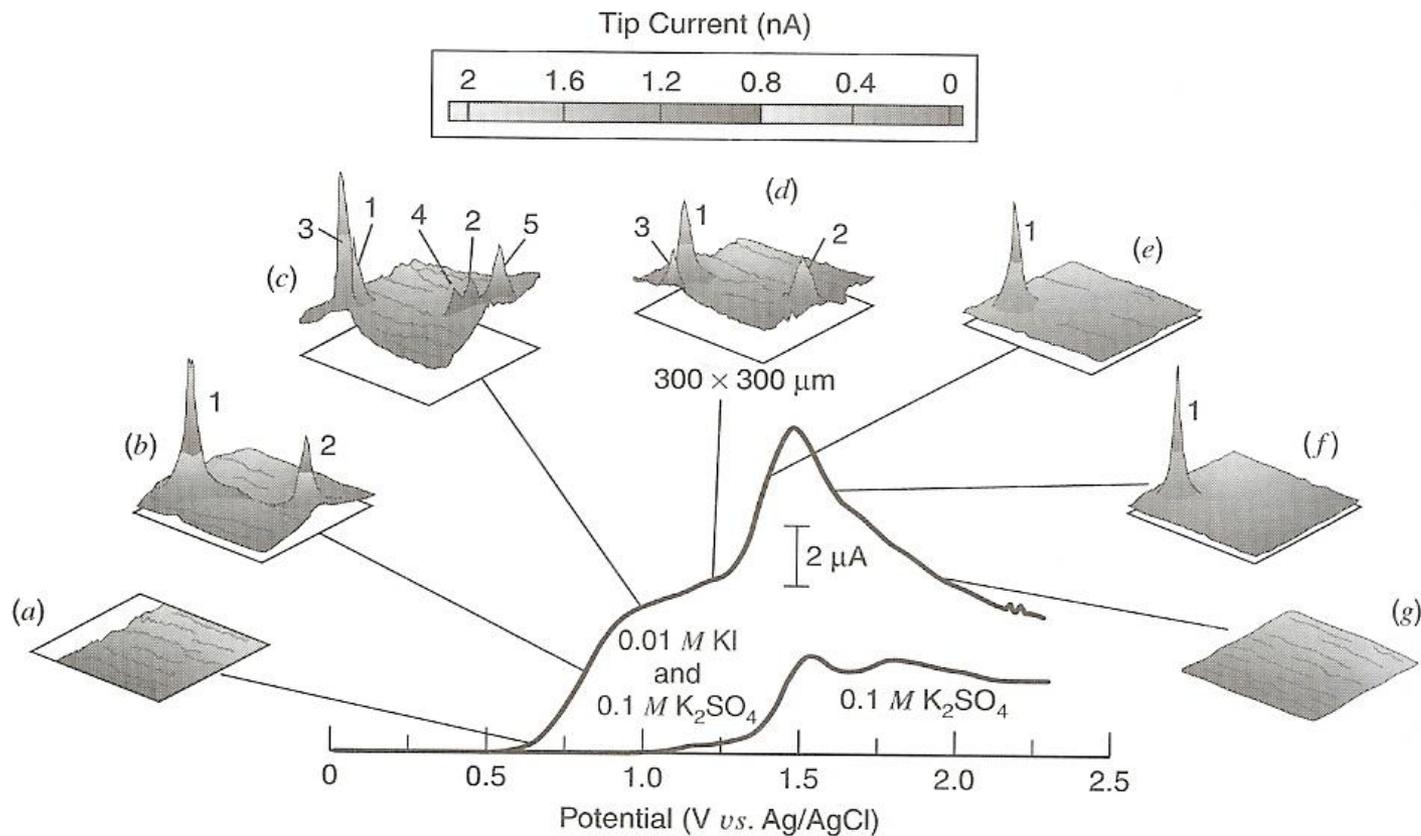
SECM approach curves for steady-state currents

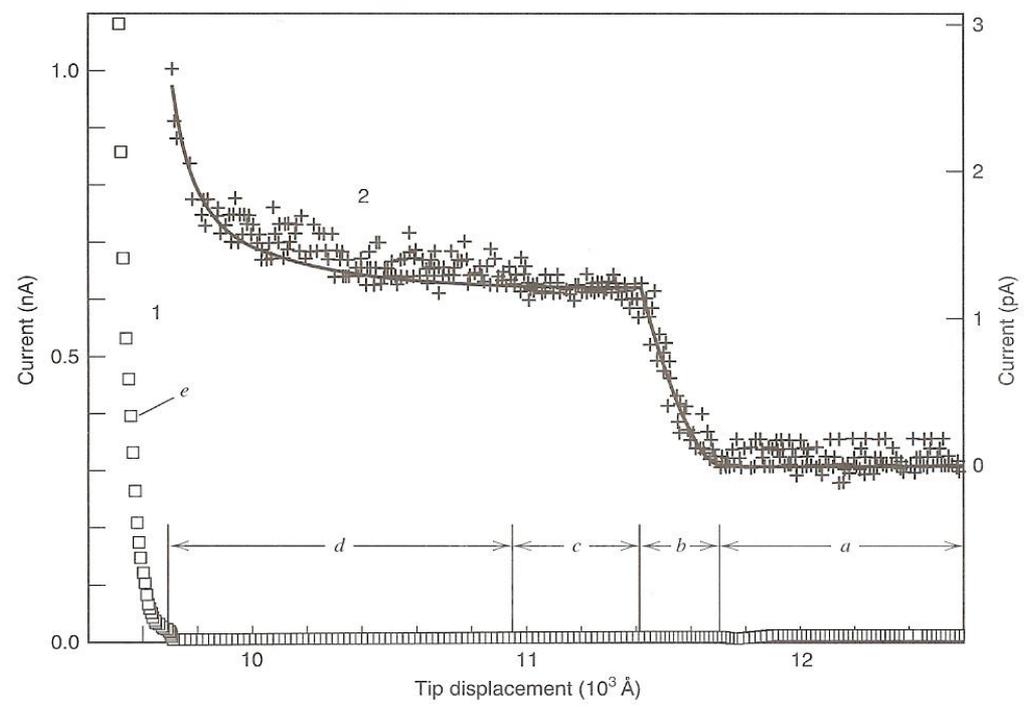
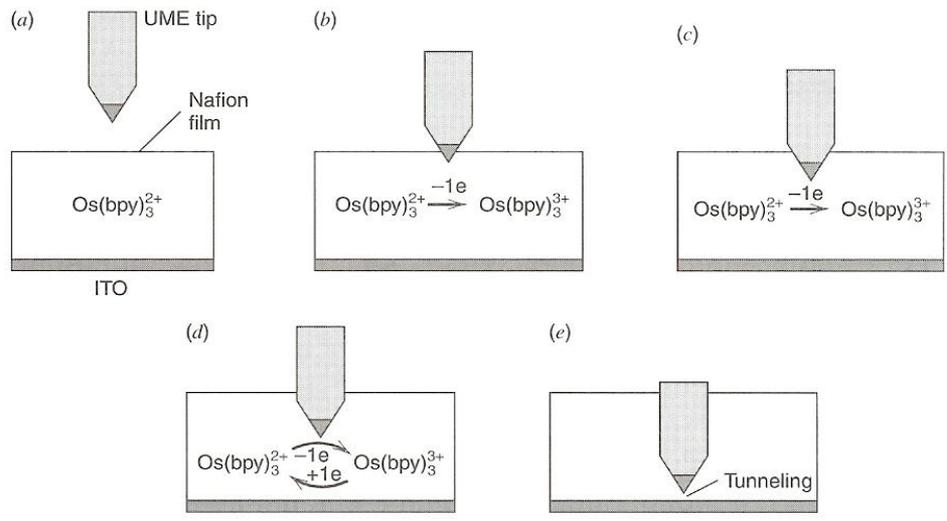




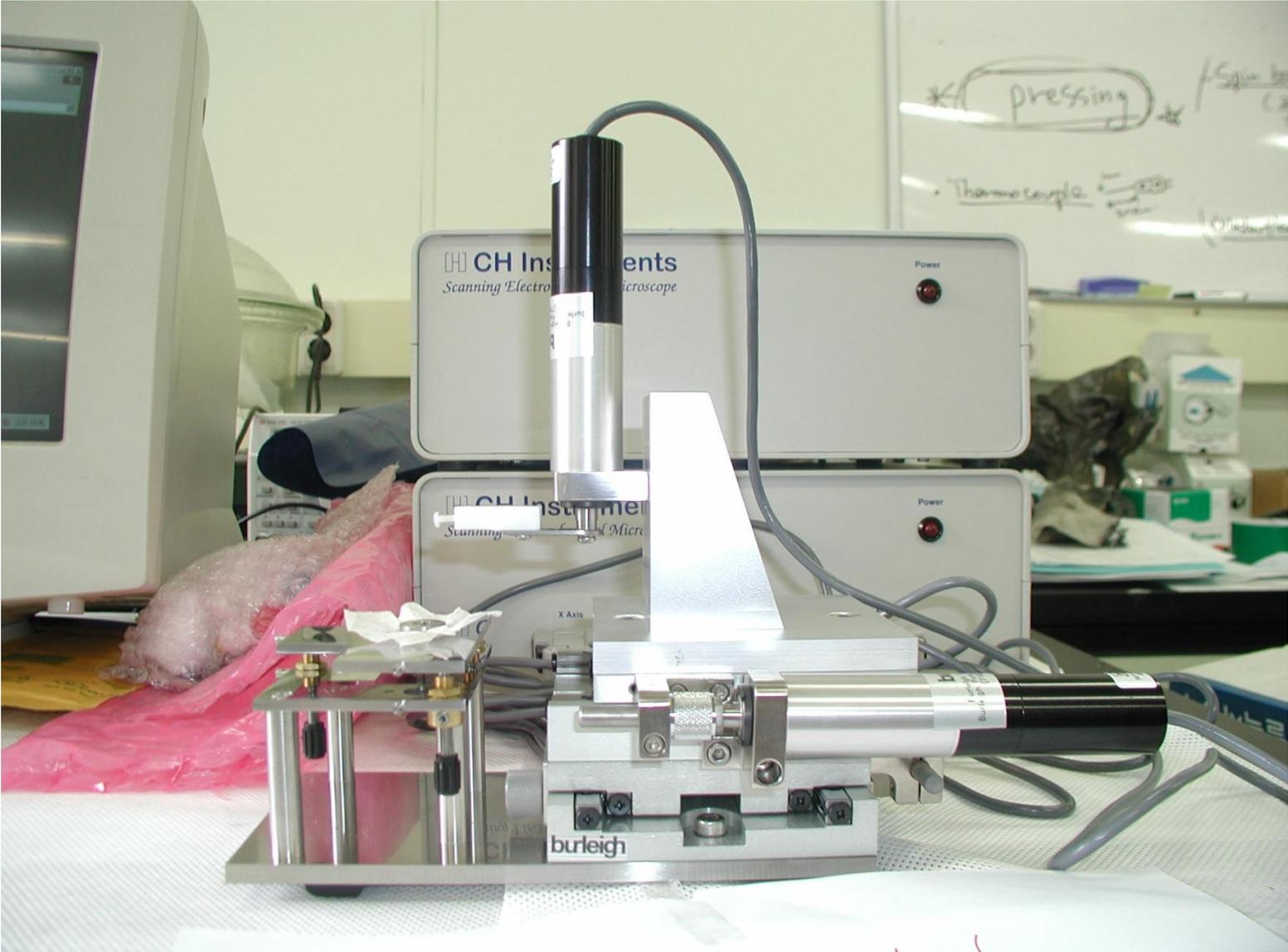
Imaging surface topography & reactivity

Ta oxide formation on Ta

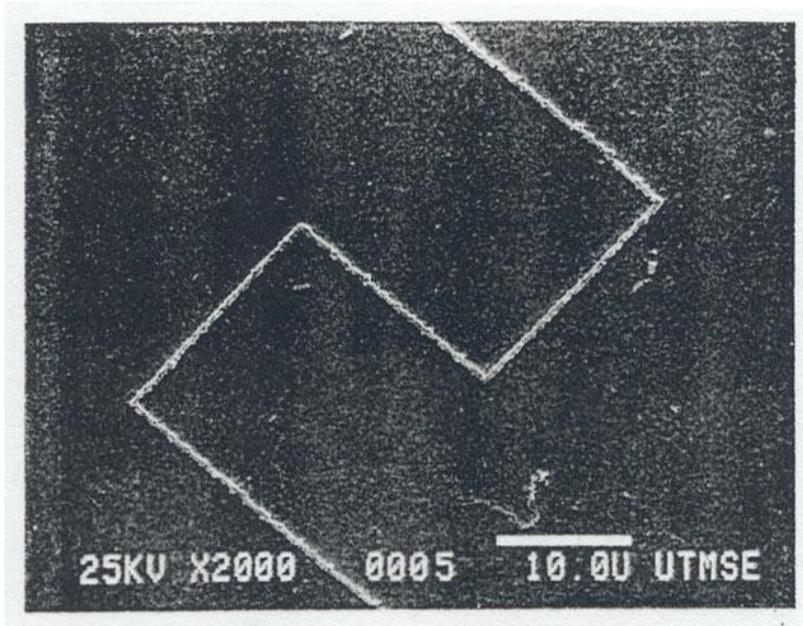




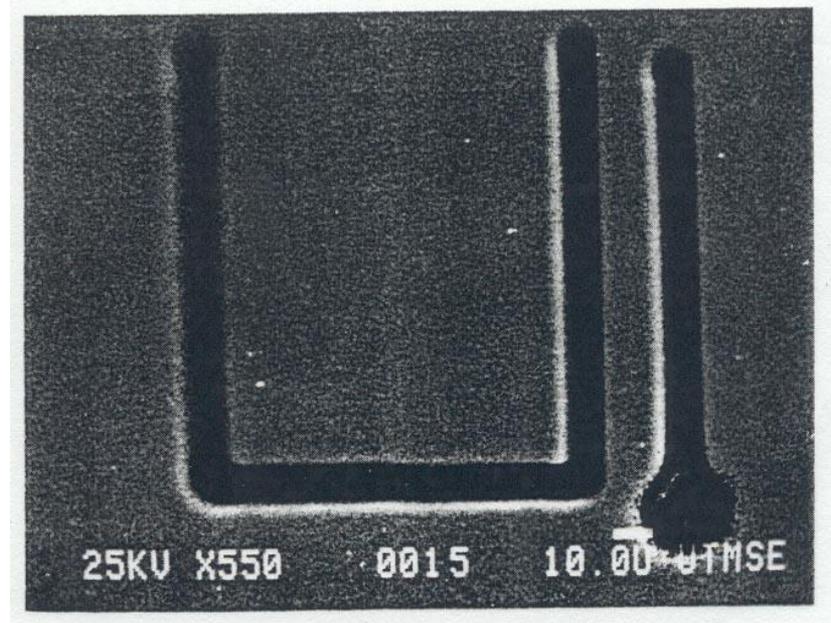
Commercialized SECM



SECM applications



Ag line formation



Electrochemical Cu etching